

Fig. 7

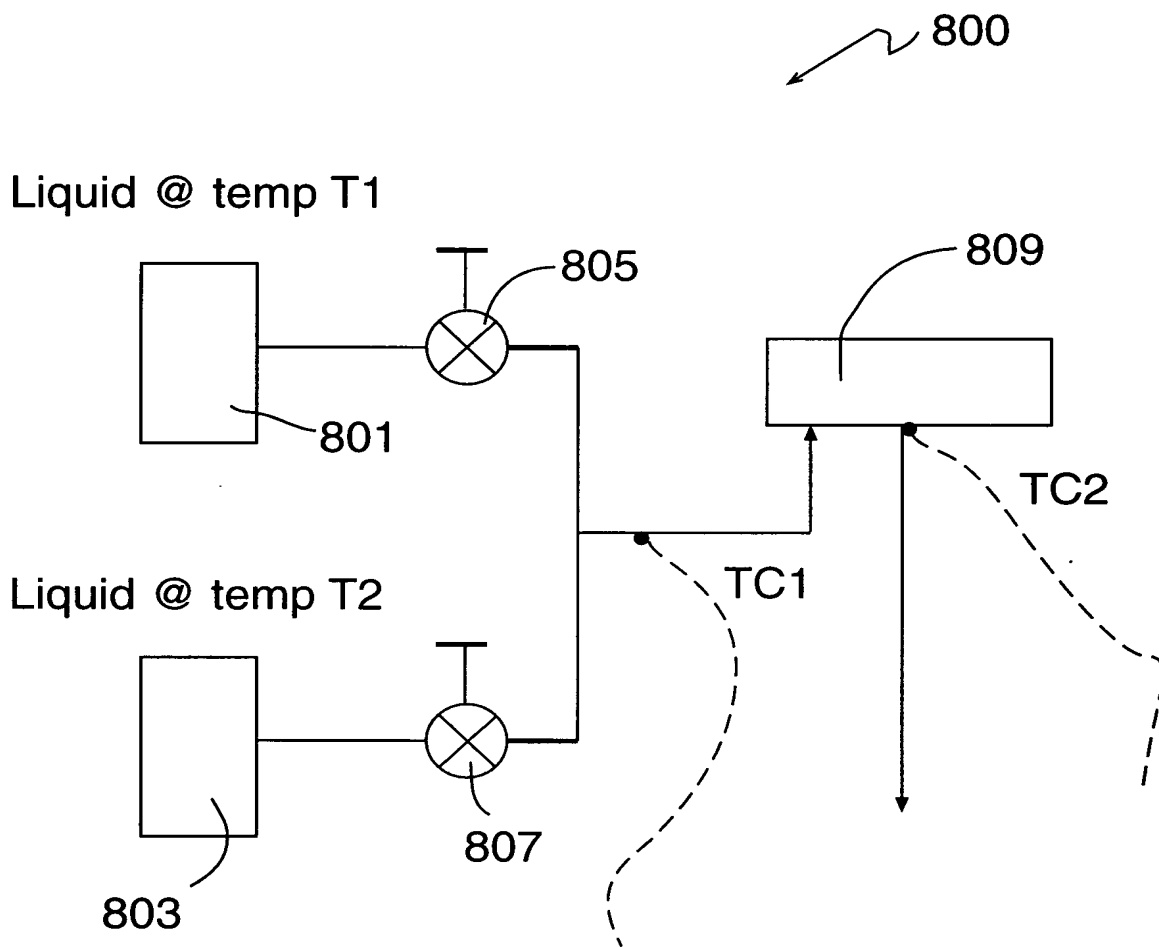
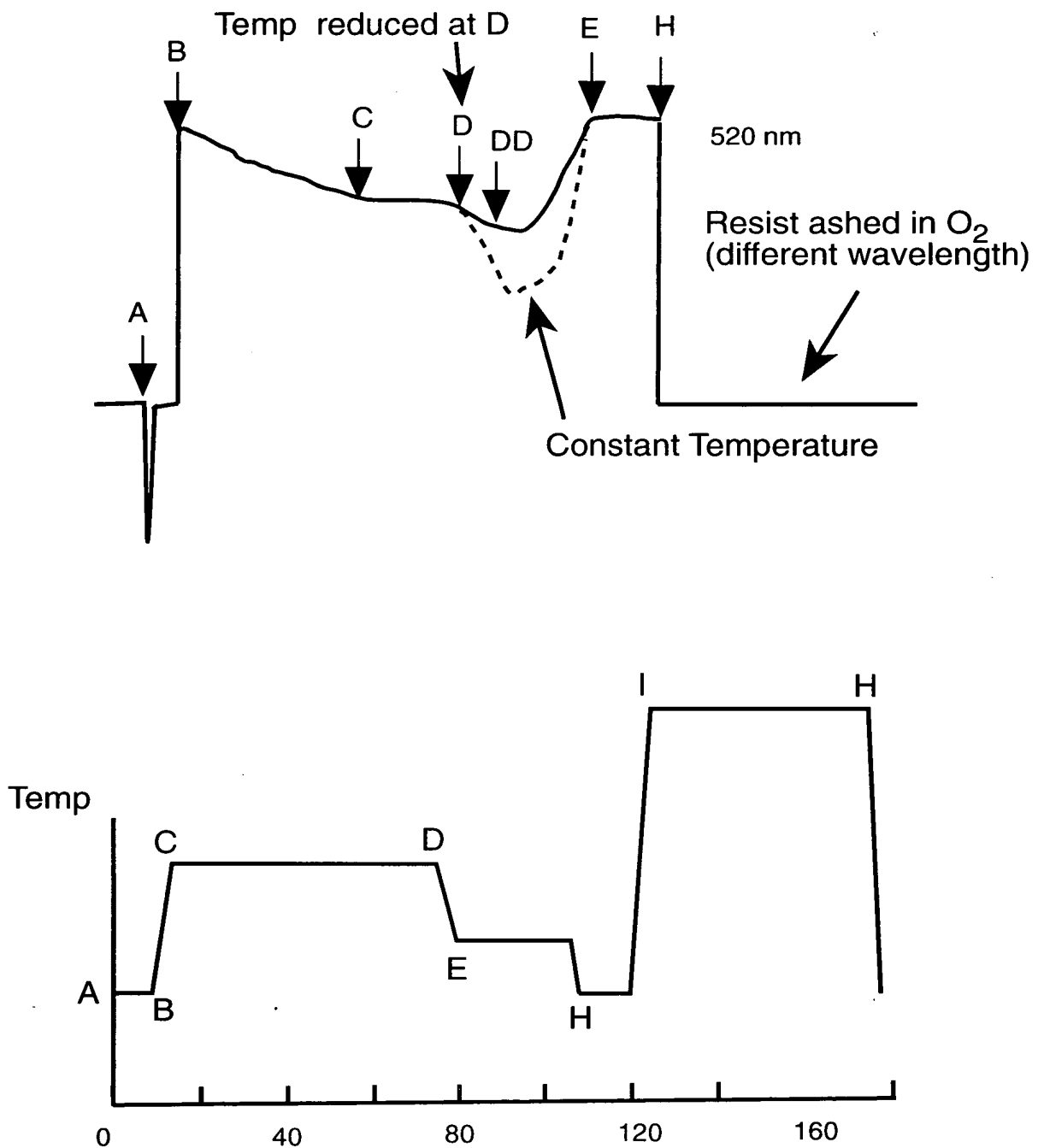


Fig. 8



A. SF₆ native oxide "breakthrough"
 B. Cl₂ plasma is ignited
 C. WSi_x begins to clear (endpoint)
 D. Polysilicon is exposed
 E. Polysilicon cleared to oxide

H. Plasma extinguished and O₂ feed gas flow is started
 I. O₂ plasma is started
 J O₂ plasma is extinguished.

Fig. 10

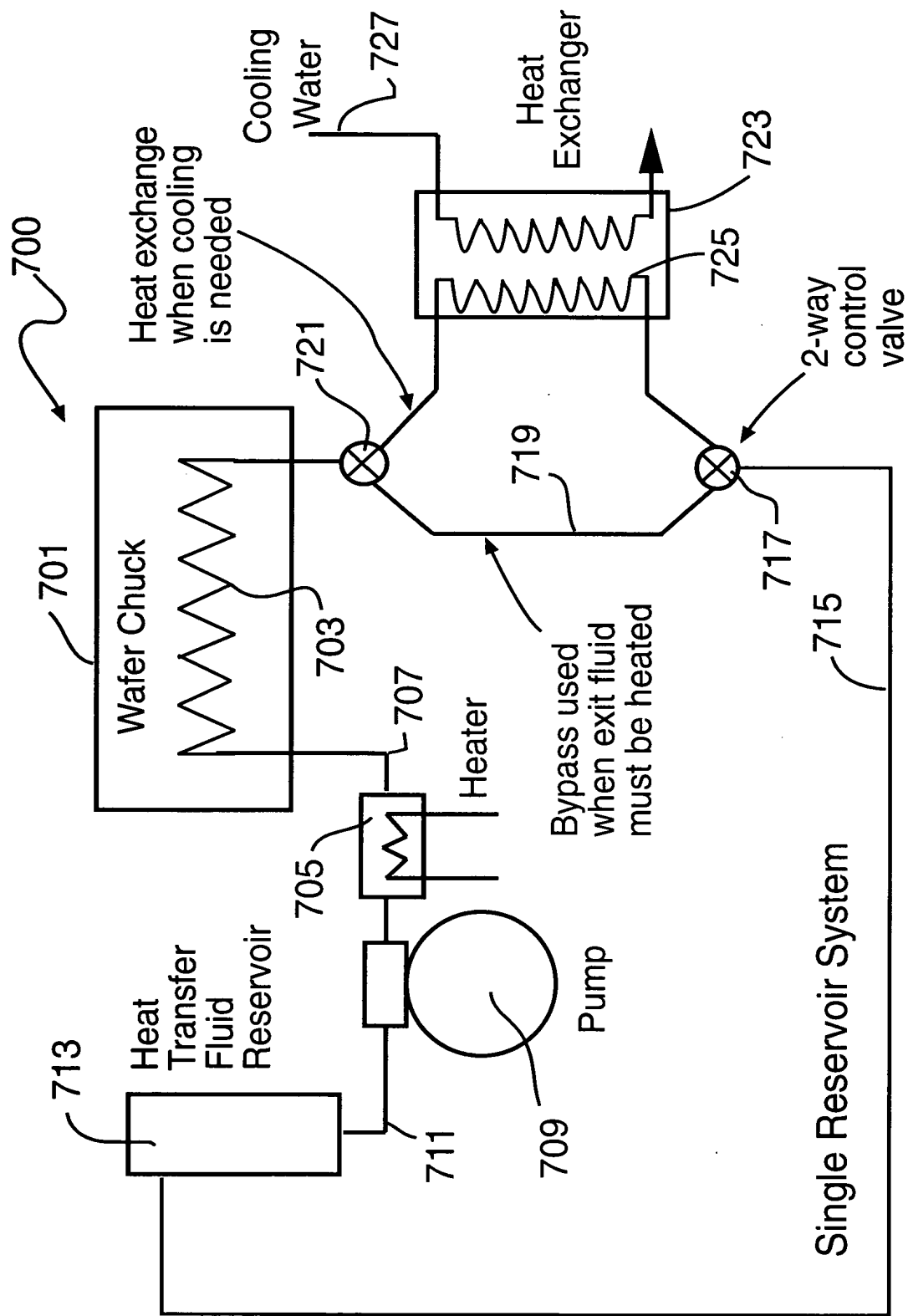


Fig. 7

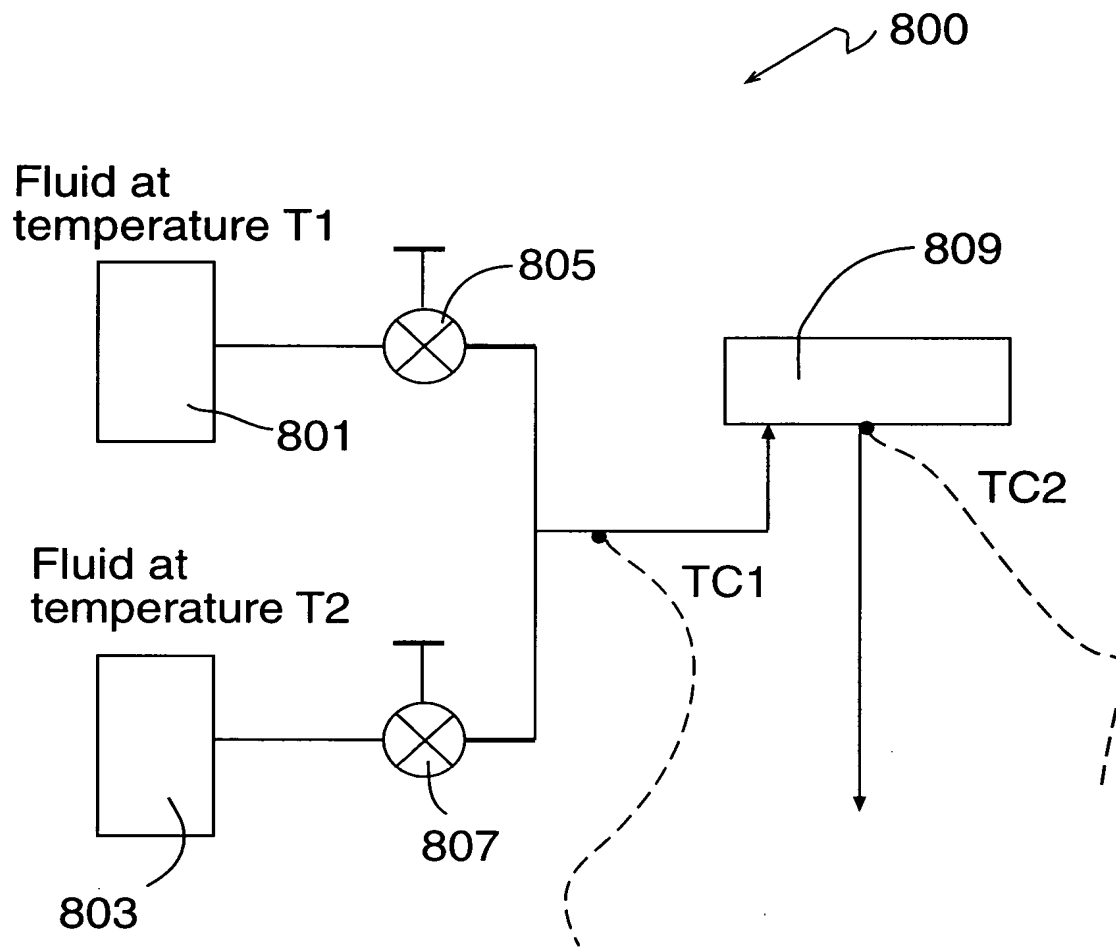
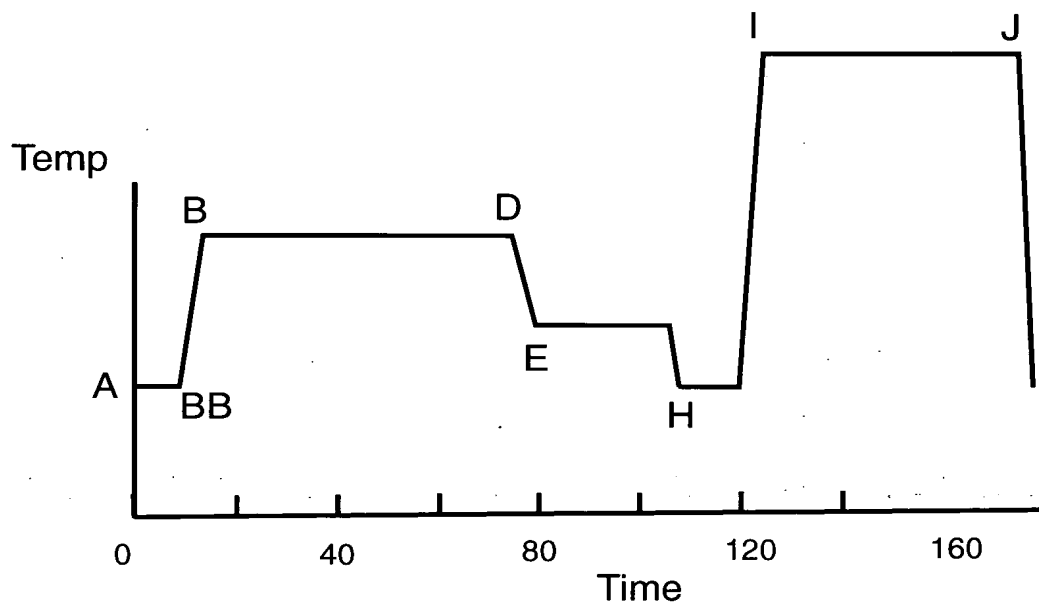
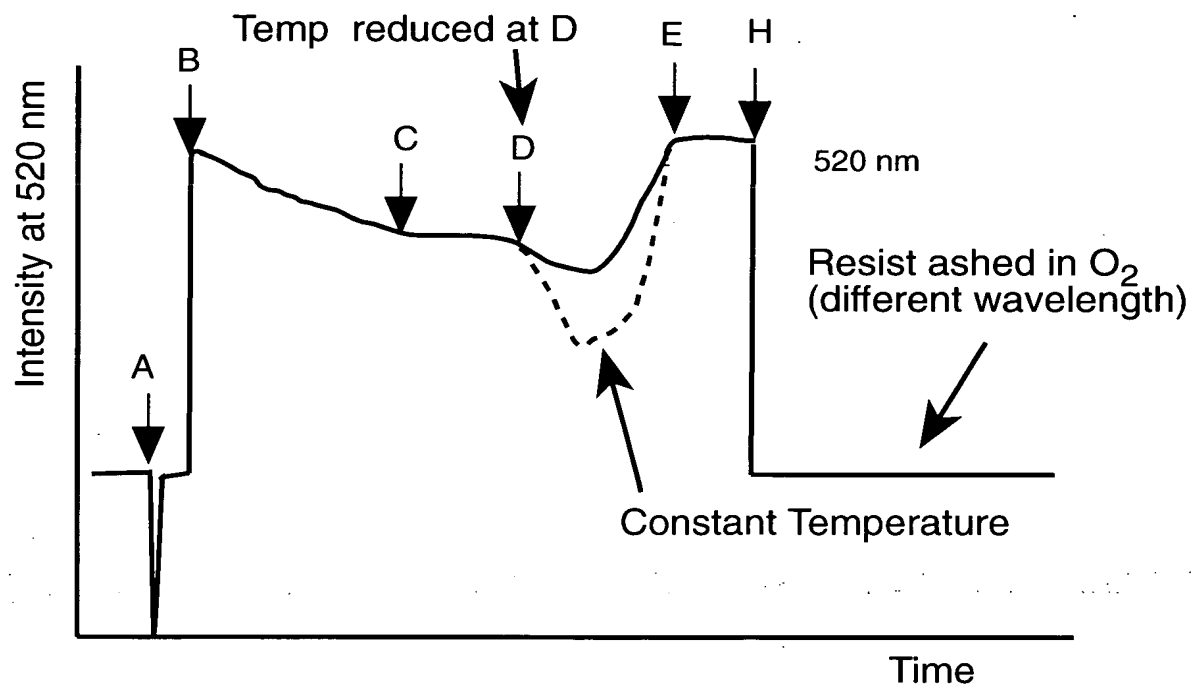


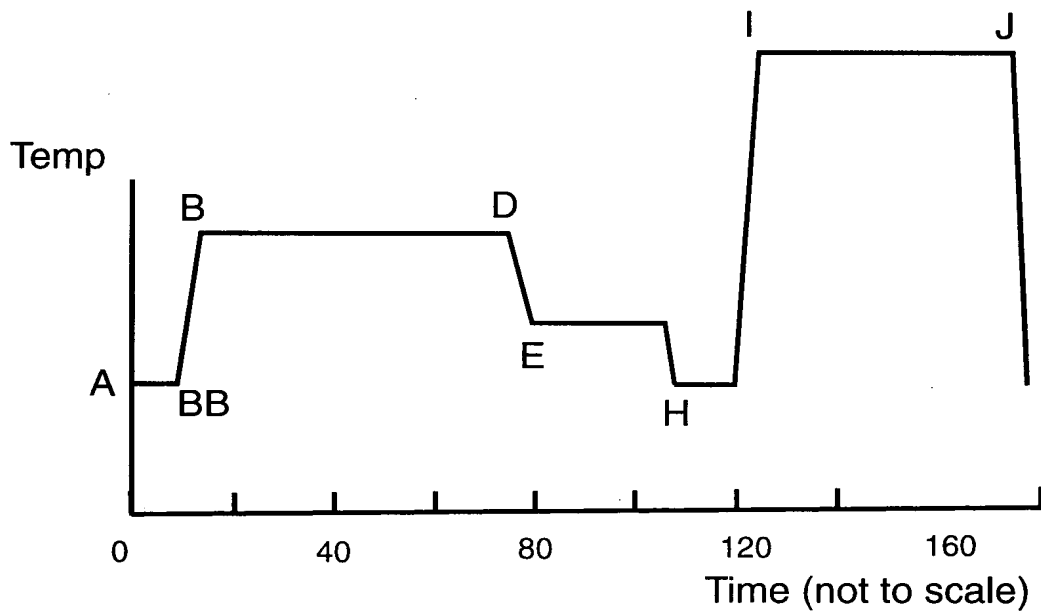
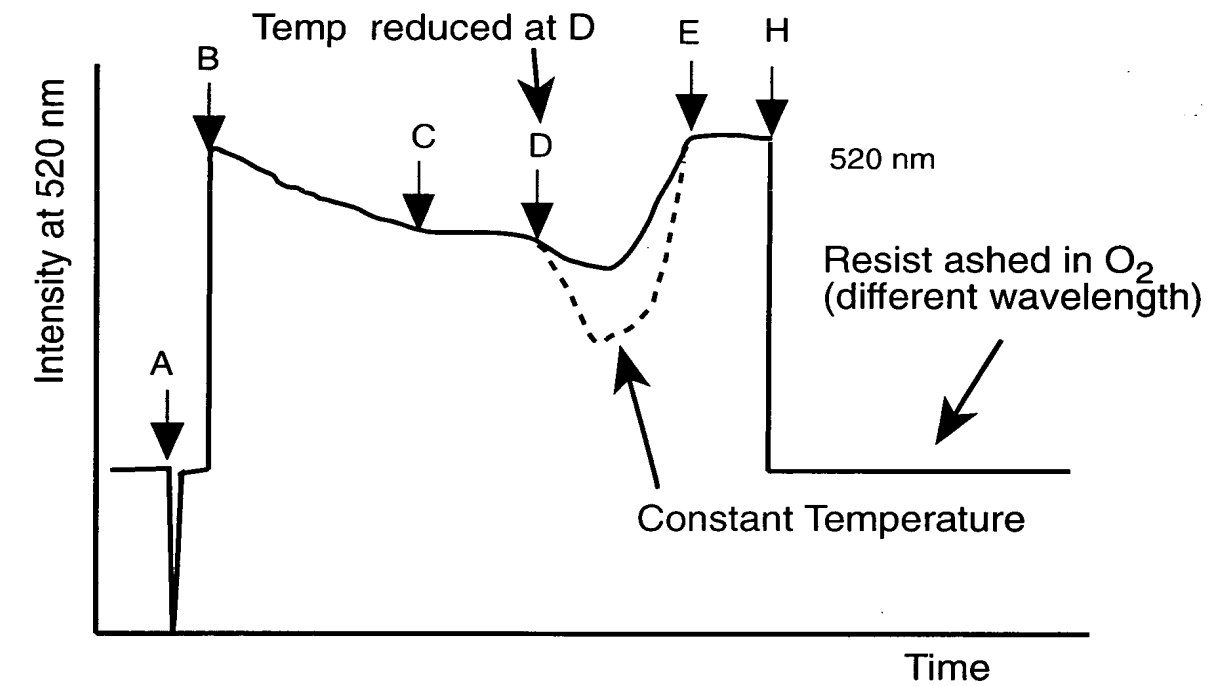
Fig. 8



A. SF₆ native oxide "breakthrough"
 B. Cl₂ plasma is ignited
 C. WSi_x begins to clear (endpoint)
 D. Polysilicon is exposed
 E. Polysilicon cleared to oxide

H. Plasma extinguished and O₂ feed gas flow is started
 I. O₂ plasma is started
 J. O₂ plasma is extinguished.

Fig. 10



- A. SF₆ native oxide "breakthrough"
- B. Cl₂ plasma is ignited
- C. WSi_x begins to clear (endpoint)
- D. Polysilicon is exposed
- E. Polysilicon cleared to oxide

- H. Plasma extinguished and O₂ feed gas flow is started
- I. O₂ plasma is started
- J O₂ plasma is extinguished.

Fig. 10

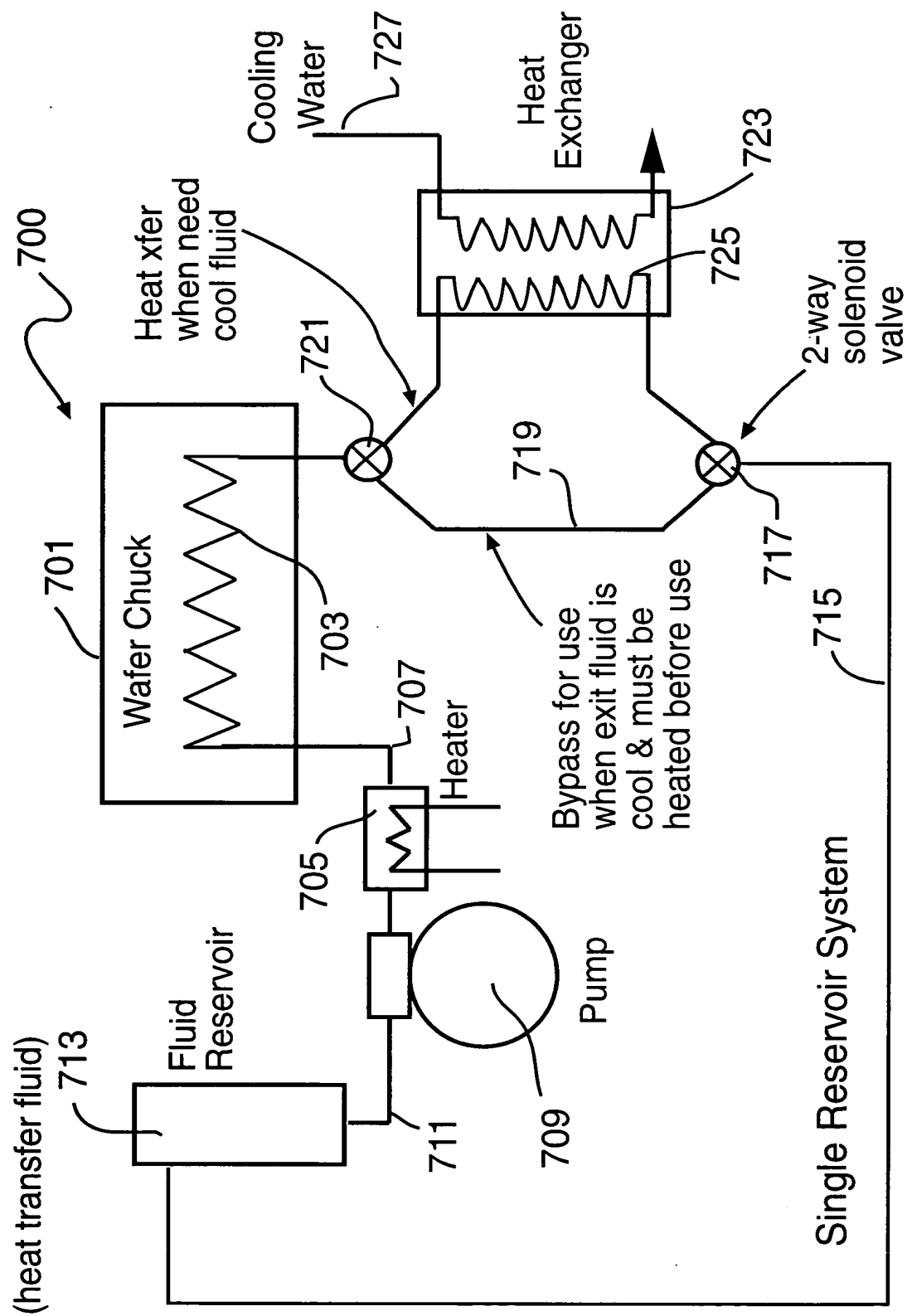


Fig. 7

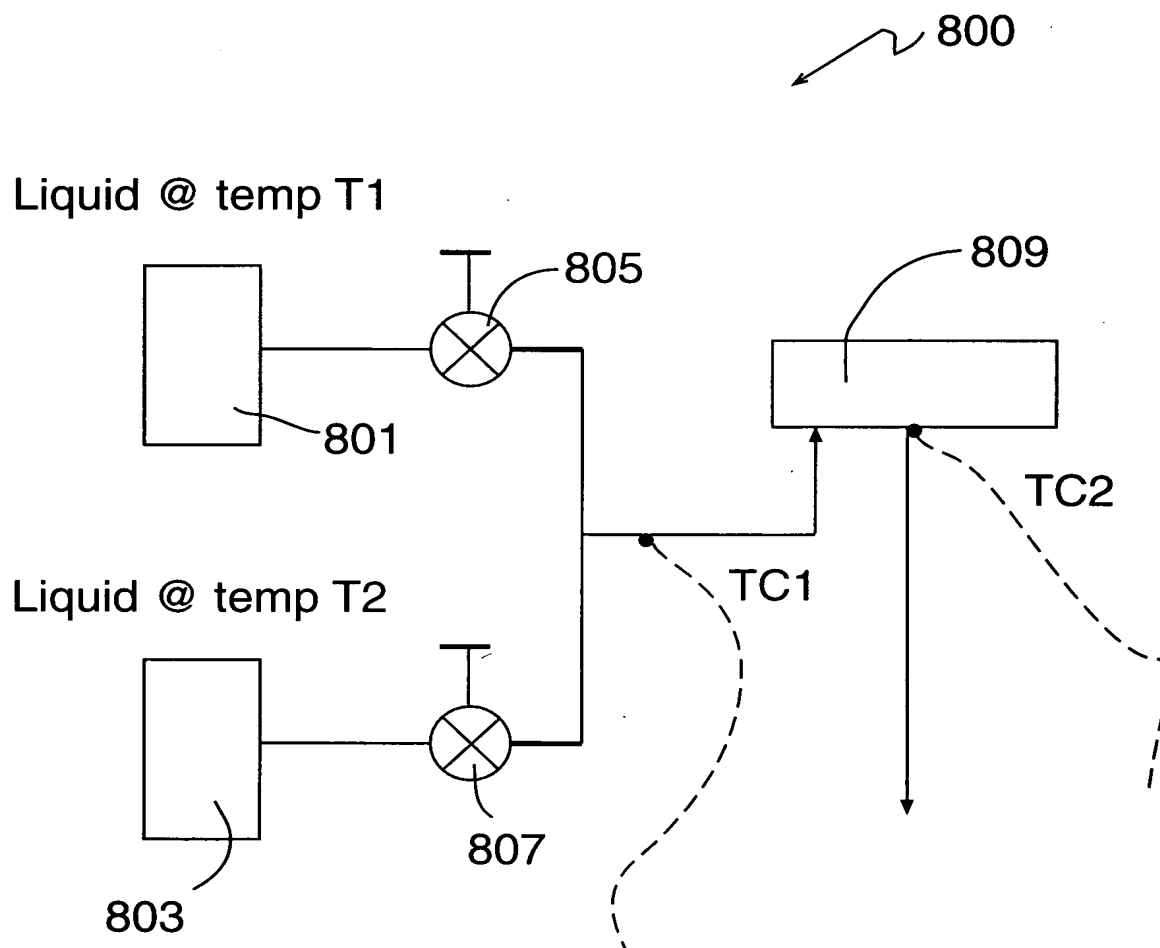
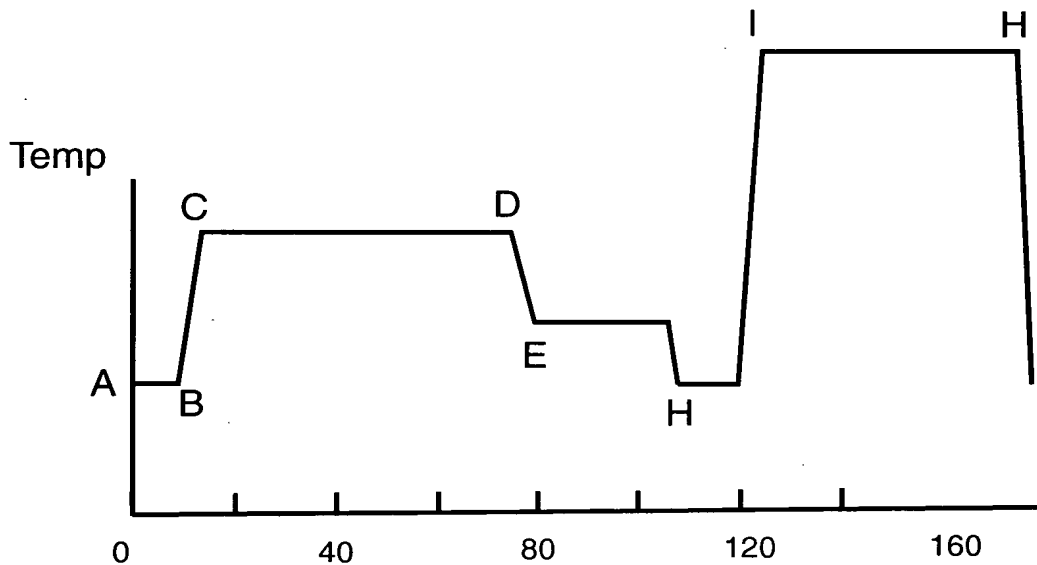
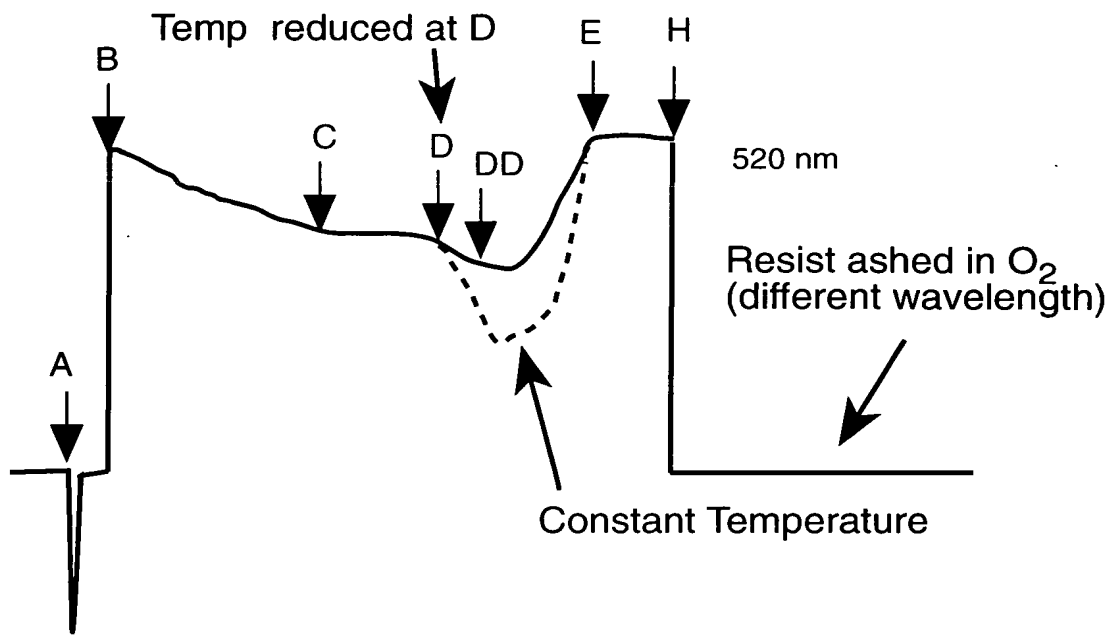


Fig. 8



A. SF₆ native oxide "breakthrough"
 B. Cl₂ plasma is ignited
 C. WSi_x begins to clear (endpoint)
 D. Polysilicon is exposed
 E. Polysilicon cleared to oxide

H. Plasma extinguished and O₂ feed gas flow is started
 I. O₂ plasma is started
 J. O₂ plasma is extinguished.

Fig. 10

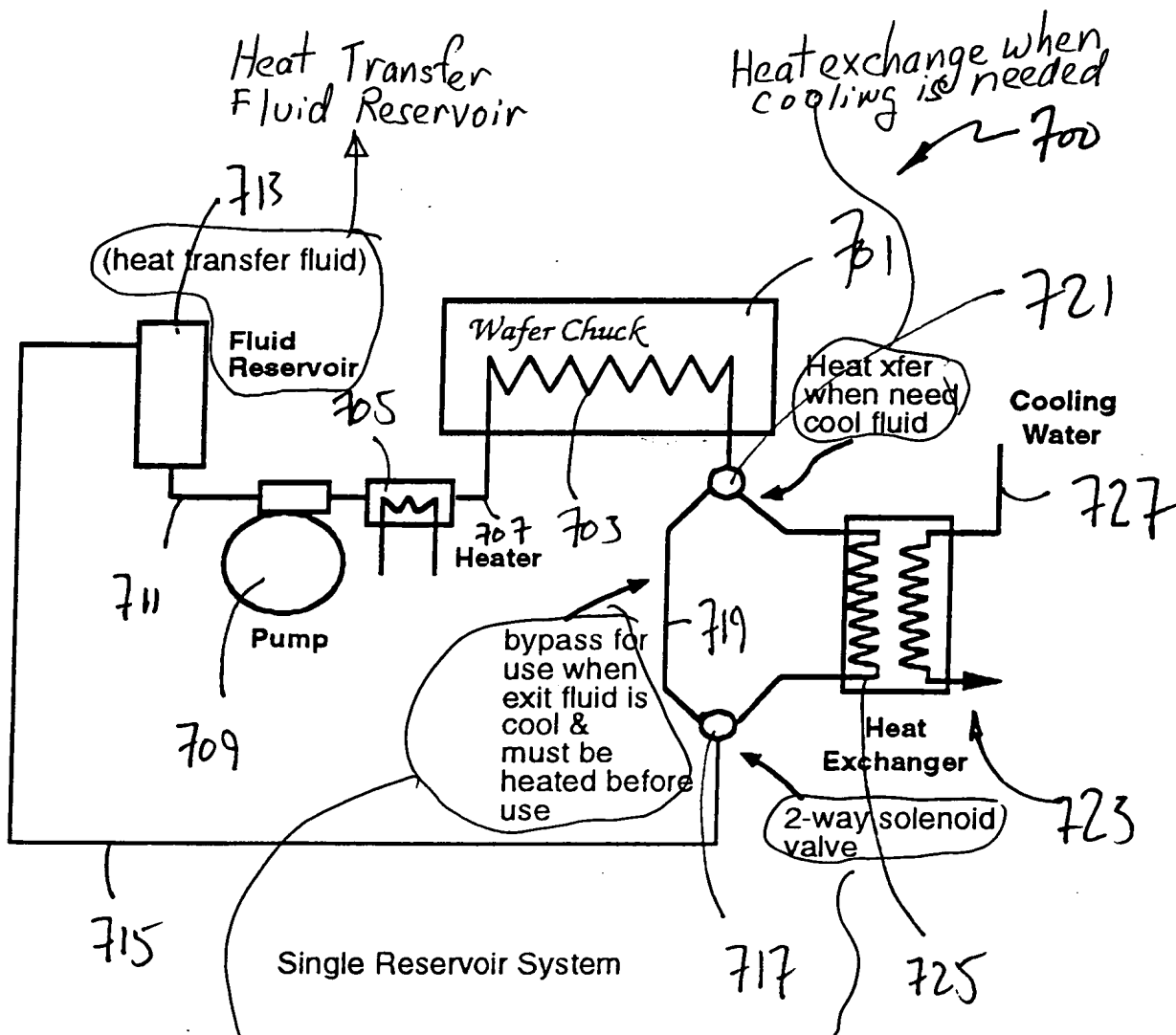


FIG. 7

Bypass used when exit fluid must be heated

2-way control valve

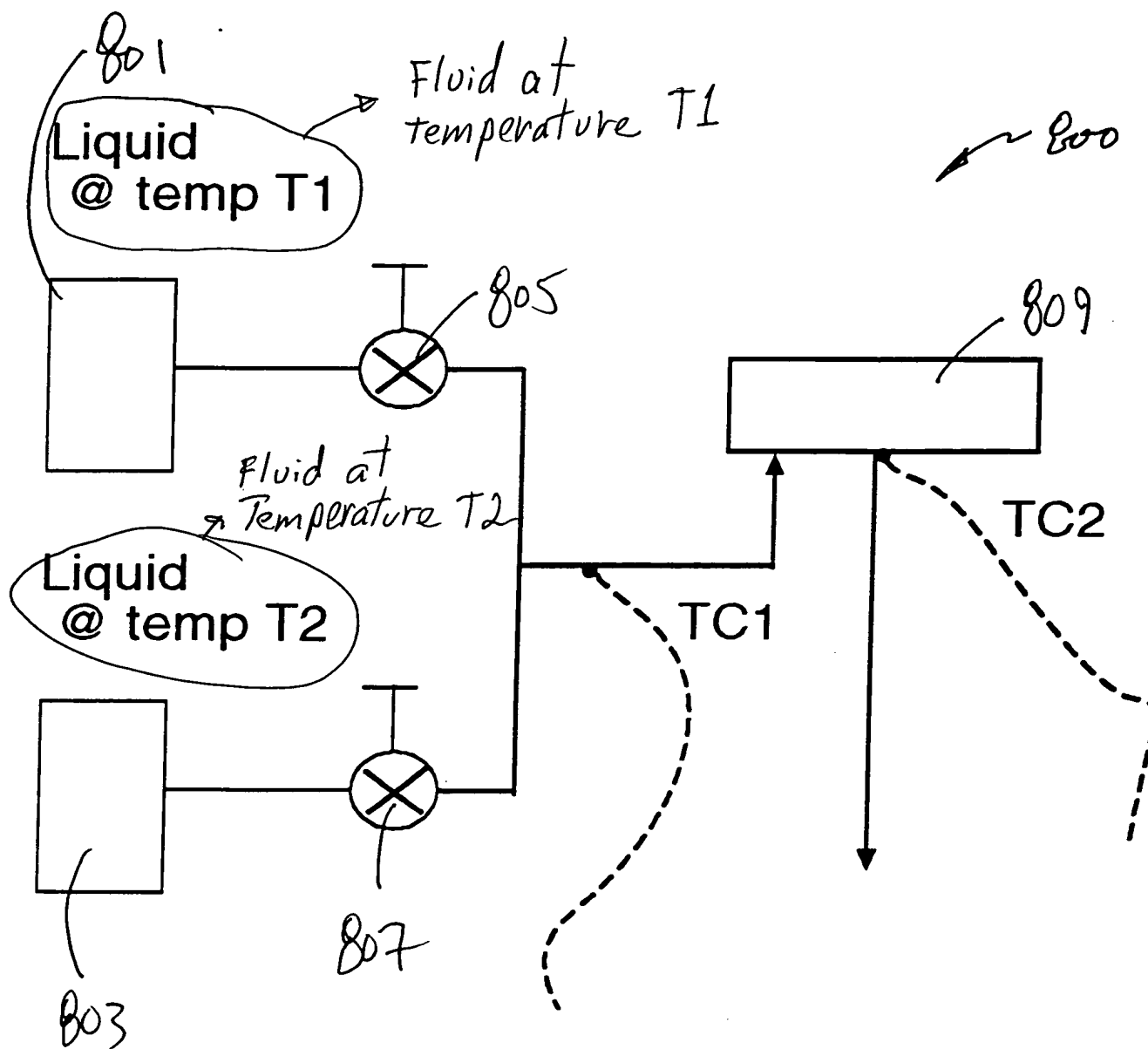
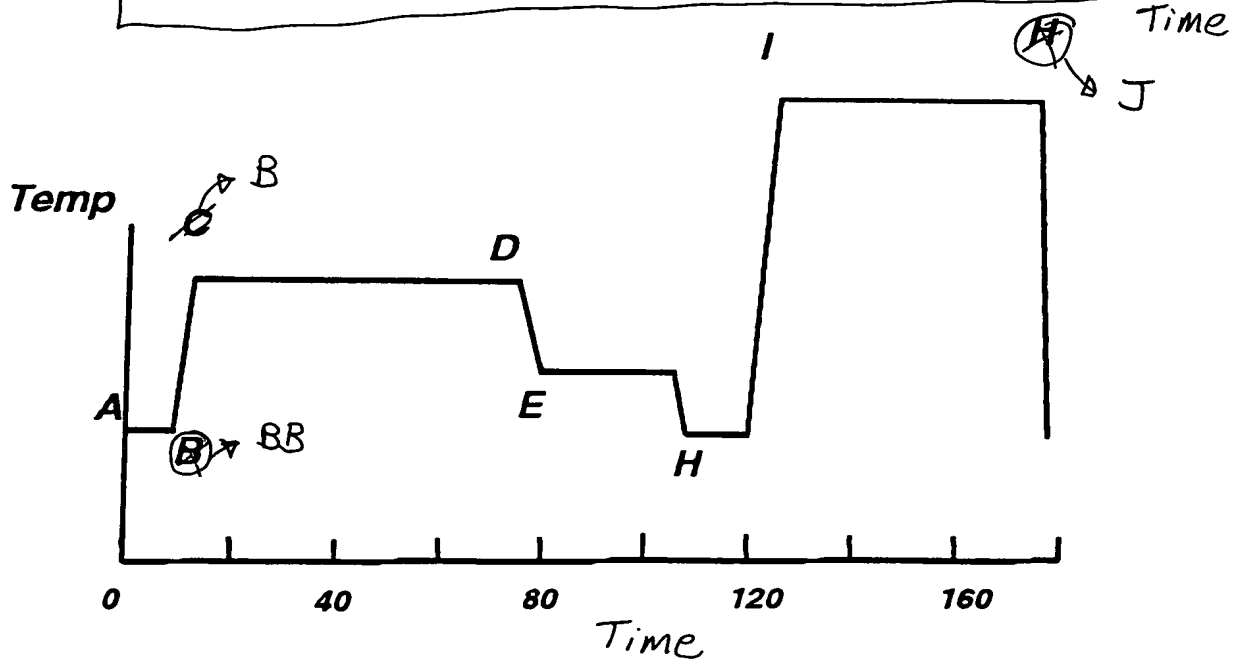
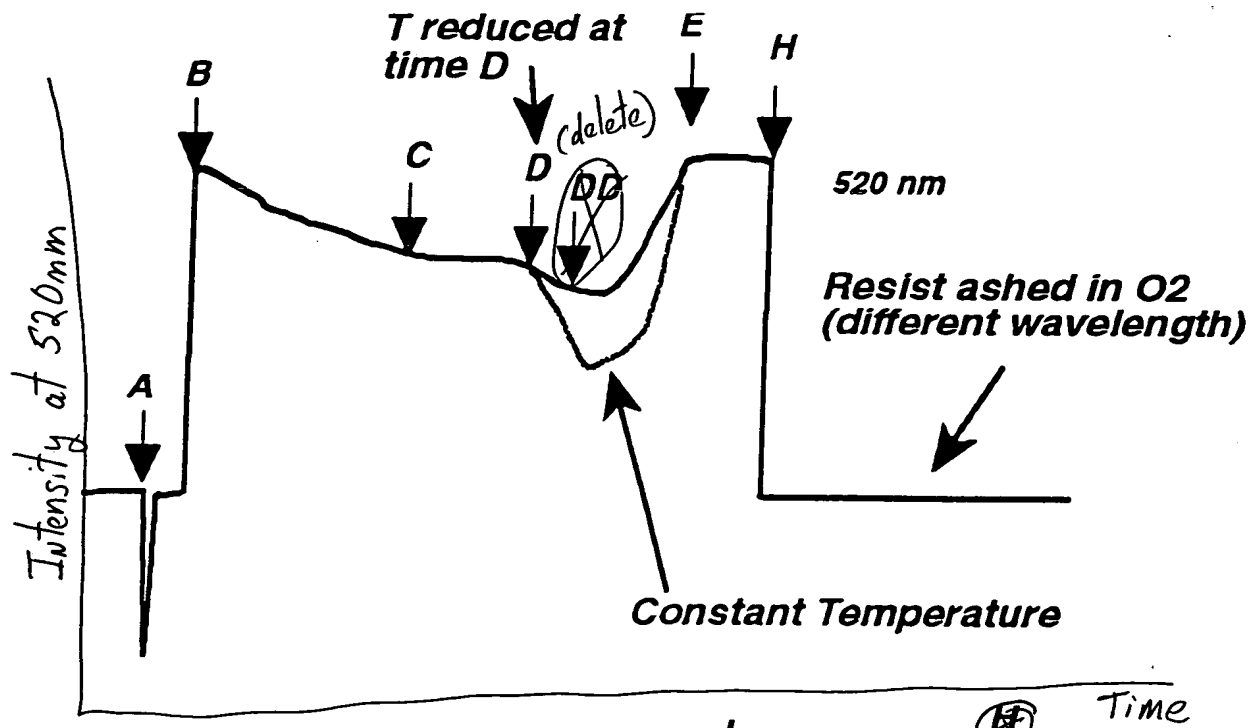


FIG. 8



- A. SF_6 native oxide "breakthrough"
- B. Cl_2 plasma is ignited
- C. WSi_x begins to clear (endpoint)
- D. Polysilicon is exposed
- E. Polysilicon cleared to oxide
- H. Plasma extinguished and O_2 feed gas flow is started
- I. O_2 plasma is started
- J O_2 plasma is extinguished.

FIG. 10